



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

*: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-12-19
Contact Name *	Refer to Supplier comment section	Contact Title	Refer to Supplier comment section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMG Material Declaration Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
LIS3DHTR	G53N*MV36BFA	A	CA2A	2016-12-19
	Amount	UoM	Unit type	ST ECOPACK Grade
	19.0	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Gold (Ni/Au), electrolytic	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
LGA	3x3x1	16	No lead	
Comment	Package: 3N LLGA 3X3X1.0 16L - FOR SENSOR			

QueryList : ROHS directive 2011/65/EU _ANNEX IV	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description
7c-1	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	GS3N*MV36BFA									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Dies	Other inorganic materials	3.217	mg	supplier	die	Silicon (Si)	7440-21-3		2.980	mg	926329	156842				
				supplier	metallisation	Aluminium (Al)	7429-90-5		0.006	mg	1865	316				
				supplier	metallisation	Copper (Cu)	7440-50-8		0.016	mg	4974	842				
				supplier	metallisation	Tantalum (Ta)	7440-25-7		0.003	mg	933	158				
				supplier	metallisation	Titanium (Ti)	7440-32-6		0.002	mg	622	105				
				supplier	Passivation	Silicon Nitride (SiN)	12033-89-5		0.006	mg	1865	316				
				supplier	passivation	Silicon Oxide	7631-86-9		0.034	mg	10569	1789				
				JIG - R	die glass coating	Lead-Borate Glass	65997-18-4	7c-I-Electrical and electron	0.170	mg	52844	8947				
				substrate	Other Organic Materials	4.520	mg	supplier	core material	Bismaleimide (B)	105391-33-1		0.256	mg	56631	13474
								supplier	core material	Triazine (T)	25722-66-1		0.256	mg	56631	13474
supplier	core material	Fiber glass	65997-17-3						0.763	mg	168788	40158				
supplier	core material	Thermosetting resin	54208-63-8						0.428	mg	94681	22526				
supplier	core material	metal hydroxide	21645-51-2						0.017	mg	3761	895				
supplier	core material	Calcium sulfate	7778-18-9						0.009	mg	1991	474				
supplier	core material	Zinc hydroxide	20427-58-1						0.005	mg	1106	263				
supplier	Solder mask	Barium sulfate	7727-43-7						0.112	mg	24776	5895				
supplier	Solder mask	Acrylic resin	9003-01-4						0.173	mg	38270	9105				
supplier	Solder mask	Epoxy resin	29690-82-2						0.136	mg	30085	7158				
supplier	Solder mask	Biphenyl epoxy resin	85954-11-6						0.084	mg	18582	4421				
supplier	Solder mask	Talc containing no asbestiform fibers	14807-96-6						0.065	mg	14379	3421				
supplier	Solder mask	Methoxymethylethoxy propanol	34590-94-8						0.019	mg	4203	1000				
supplier	Solder mask	Amorphous silica	7631-86-9						0.012	mg	2655	632				
supplier	Solder mask	3-methyl-methoxy-buthyl	103429-90-9						0.008	mg	1770	421				
supplier	Solder mask	Silica Cristobalite	14464-46-1						0.006	mg	1327	316				
supplier	Solder mask	Morpholine derivative	Proprietary						0.003	mg	664	158				
supplier	metallisation	Copper (Cu)	7440-50-8						2.147	mg	474951	113000				
supplier	metallisation	Nickel (Ni)	7440-02-0						0.019	mg	4181	995				
supplier	metallisation	Gold (Au)	7440-57-5						0.003	mg	567	135				
Die attach	Other inorganic materials	0.072	mg	supplier	tape	epoxy resin	Proprietary		0.045	mg	625000	2368				
				supplier	tape	polyolefin	9003-07-0		0.023	mg	319444	1211				
				supplier	tape	Diphenol Propane Diglycidyl Ether	1675-54-3		0.004	mg	55556	211				
Bonding wire	Precious metals	0.441	mg	supplier	wire	Gold (Au)	7440-57-5		0.437	mg	990930	23000				
				supplier	wire	Palladium (Pd)	7440-05-3		0.004	mg	9070	211				
encapsulation	Other Organic Materials	10.750	mg	supplier	mold compound	Silica, vitreous	60676-86-0		8.546	mg	794977	449789				
				supplier	mold compound	Silica	7631-86-9		1.075	mg	100000	56579				
				supplier	mold compound	Epoxy Resin	90598-46-2		0.430	mg	40000	22632				
				supplier	mold compound	Epoxyde Bisphenol A Resin	25068-38-6		0.376	mg	34977	19789				
				supplier	mold compound	Phenol Resin	9003-35-4		0.269	mg	25023	14158				
				supplier	mold compound	Carbon black	1333-86-4		0.054	mg	5023	2842				